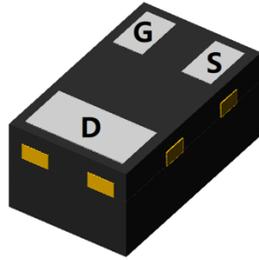


## P-Channel Enhancement Mode Field Effect Transistor

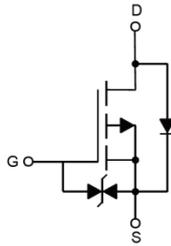


Top View



Bottom View

DFN1006-3L



### Product Summary

- $V_{DS}$  -20V
- $I_D$  -0.65A
- $R_{DS(ON)}$  ( at  $V_{GS}=-4.5V$ ) < 850 mohm
- $R_{DS(ON)}$  ( at  $V_{GS}=-2.5V$ ) < 1200 mohm
- $R_{DS(ON)}$  ( at  $V_{GS}=-1.8V$ ) < 2000 mohm
- ESD Protected Up to 2.0KV (HBM)

### General Description

- Trench Power LV MOSFET technology
- High Density Cell Design for Low  $R_{DS(ON)}$
- High Speed switching
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Interfacing, Logic switch
- Load switch
- Power management

### ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-source Voltage	$V_{DS}$	-20	V
Gate-source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current	$I_D$	$T_A=25^\circ C$ Steady State	-0.65
		$T_A=70^\circ C$ Steady State	-0.52
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	-2.0	A
Total Power Dissipation @ $T_A=25^\circ C$ Steady State	$P_D$	0.9	W
Thermal Resistance Junction-to-Ambient @ Steady State <sup>B</sup>	$R_{\theta JA}$	138	$^\circ C/W$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ C$

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJA3139KB	F1	9A	10000	100000	400000	7" reel



# YJA3139KB

## ■ Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, T <sub>C</sub> =25°C			-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±10V, V <sub>DS</sub> =0V		±1.5	±10	μA
		V <sub>GS</sub> = ±8V, V <sub>DS</sub> =0V		±500	±2000	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.35	-0.62	-1.2	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> =-0.5A		580	850	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> =-0.3A		855	1200	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> =-0.2A		1350	2000	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =-0.65A, V <sub>GS</sub> =0V		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				-0.65	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHZ		71		pF
Output Capacitance	C <sub>oss</sub>			20		
Reverse Transfer Capacitance	C <sub>rss</sub>			15		
Gate resistance	R <sub>g</sub>	f=1MHz, Open Drain		85		Ω
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =-4.5V, V <sub>DD</sub> =-10V, I <sub>D</sub> =-0.5A		1.24		nC
Gate Source Charge	Q <sub>gs</sub>			0.37		
Gate Drain Charge	Q <sub>gd</sub>			0.27		
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =-0.5A, di/dt=-20A/us		0.97		ns
Reverse Recovery Time	t <sub>rr</sub>			26		
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =-4.5V, V <sub>DD</sub> =-10V, R <sub>L</sub> =2.5Ω, R <sub>GEN</sub> =3Ω		4		ns
Turn-on Rise Time	t <sub>r</sub>			19		
Turn-off Delay Time	t <sub>D(off)</sub>			16		
Turn-off Fall Time	t <sub>f</sub>			25		

A. Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

B. The value of R<sub>θJA</sub> is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> = 25°C. The Power dissipation P<sub>D</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 150°C may be used if the PCB allows it to.



■ Typical Performance Characteristics

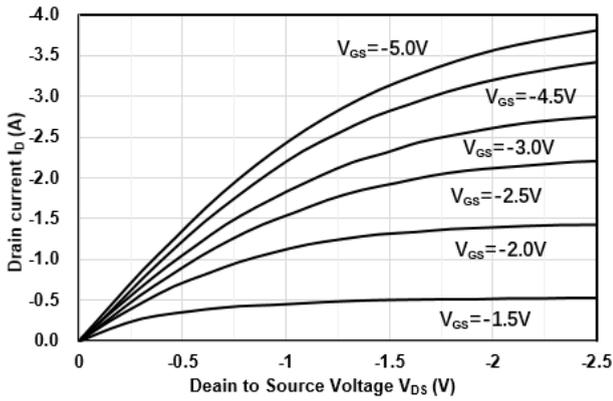


Figure1. Output Characteristics

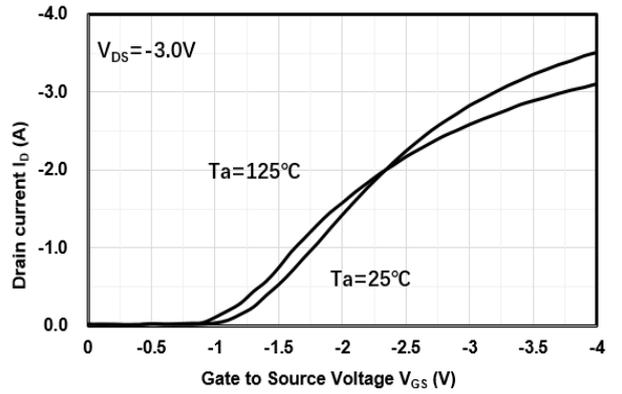


Figure2. Transfer Characteristics

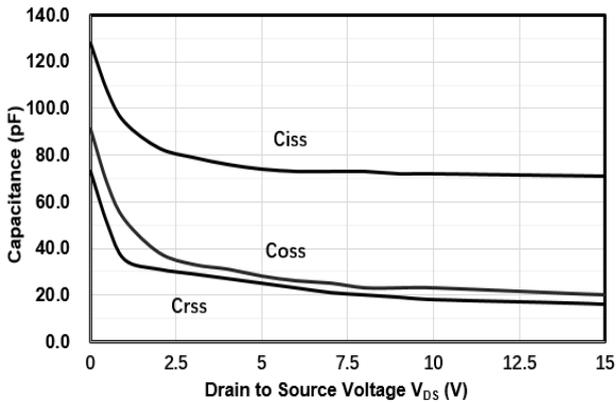


Figure3. Capacitance Characteristics

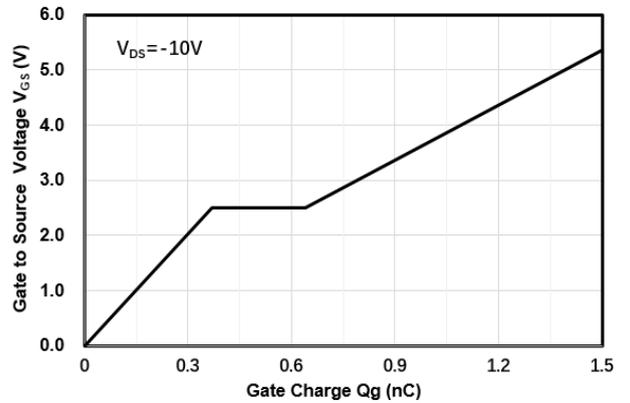


Figure4. Gate Charge

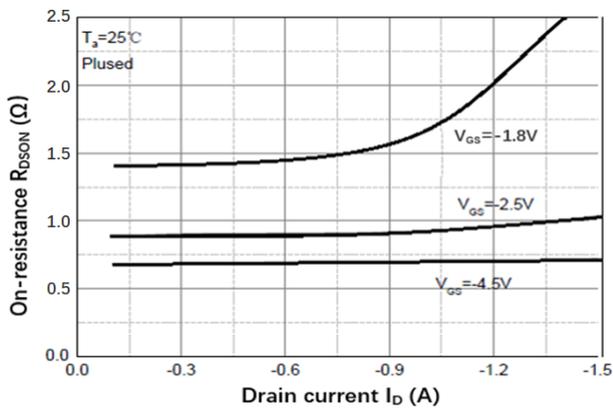


Figure5. Drain-Source on Resistance

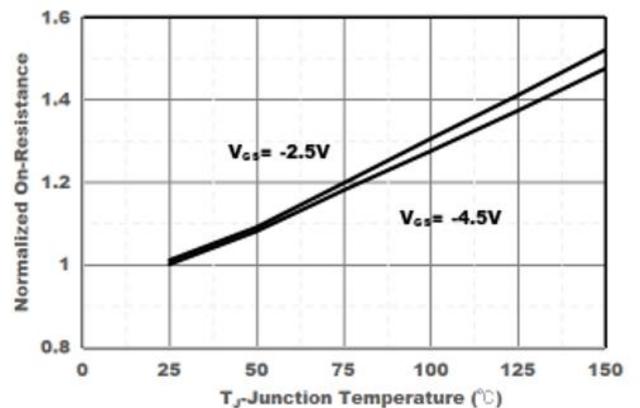


Figure6. Drain-Source on Resistance



# YJA3139KB

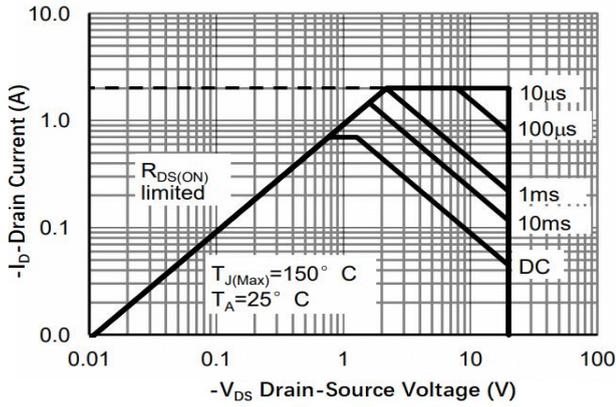


Figure7. Safe Operation Area

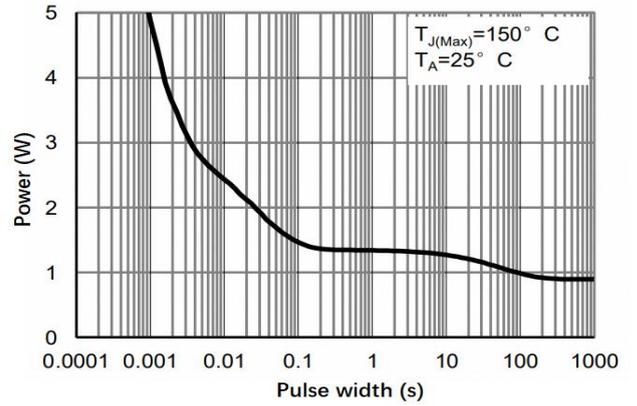


Figure8. Pulse Power Rating Junction-to Ambient

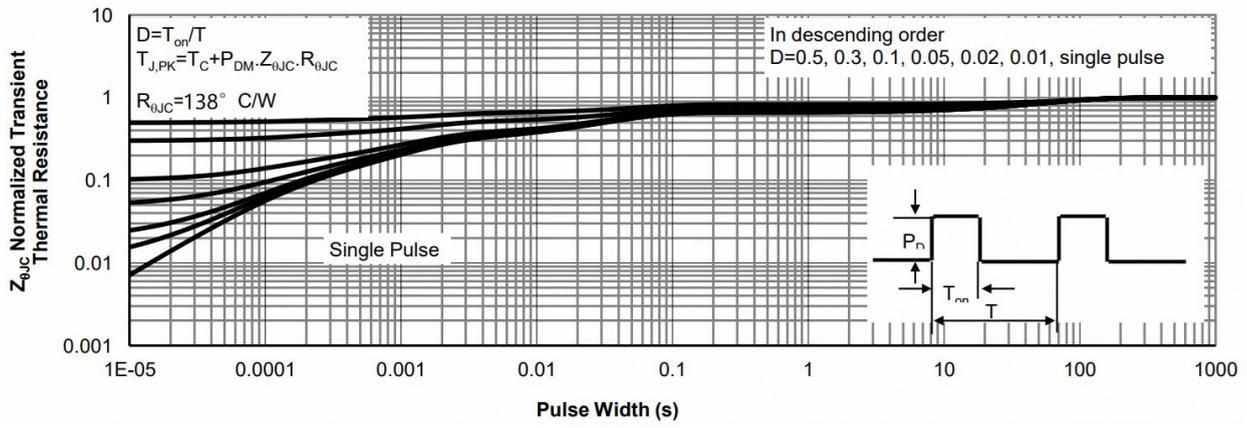
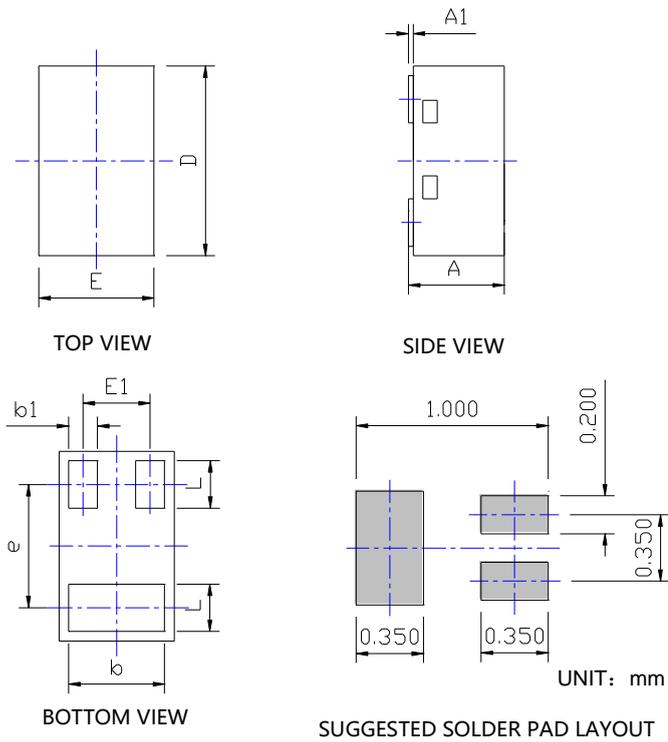


Figure9. Normalized Maximum Transient Thermal Impedance



# YJA3139KB

## ■ DFN1006-3L Package information



SYMBOL	DIMENSIONS		
	Millimeter		
	MIN.	NOM.	MAX.
A	0.42	---	0.55
A1	0.025REF		
b	0.45	0.50	0.55
b1	0.10	0.15	0.20
D	0.95	1.00	1.05
E	0.55	0.60	0.65
E1	0.35BSC		
e	0.65BSC		
L	0.20	0.25	0.30

### NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE LEAD BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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